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Part Number: [73644-3001](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position A, 144 Circuits

Documents:

3D Model	Test Summary TS-73670-990 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

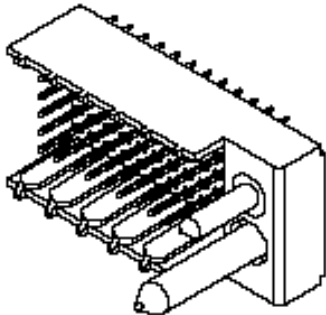
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit, Tin/Lead (SnPb)
Component Type	PCB Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
Style	N/A
UPC	800755023763

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	9.734/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73644Series](#)

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	

Termination Interface: Style

Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact

1A

Data Rate

1.0 Gbps

Real Signals (per 25mm)

75

Shielded

No

Voltage - Maximum

250V AC

Material Info

Reference - Drawing Numbers

Sales Drawing

SDA-73644-****

Test Summary

TS-73670-990

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This document was generated on 12/08/2014

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